

**AMENDMENTS TO THE CLAIMS**

*The listing of claims will replace all prior versions and listings of claims in the application:*

**Listing of Claims:**

1.     **(Previously Presented)**     A method of manufacturing an optical transceiver module, comprising:

connecting a plurality of electrical contacts of a lead frame connector to corresponding leads of an optical sub-assembly to obtain a combined structure that includes the lead frame connector and the optical sub-assembly; and

attaching the optical sub-assembly to a printed circuit board using the lead frame connector such that the lead frame connector electrically connects the optical sub-assembly to the printed circuit board and the lead frame connector provides mechanical support for the optical sub-assembly.

2.     **(Original)**     The method as defined in claim 1, wherein connecting the plurality of electrical contacts comprises:

passing each of the leads of the optical sub-assembly through a hole in the corresponding electrical contact; and

soldering the leads to the corresponding electrical contacts.

3.     **(Original)**     The method as defined in claim 2, wherein soldering the leads to the corresponding electrical contacts is performed by applying the solder to the electrical contacts at a side of the lead frame connector that is opposite a side that is adjacent to the optical sub-assembly.

4.     **(Previously Presented)**     The method as defined in claim 10, wherein connecting the plurality of leads of the lead frame connector to the corresponding conductive structures on a printed circuit board comprises:

placing the leads of the lead frame connector in contact with the corresponding conductive structures; and

reflow soldering the leads to the conductive structures.

5.     **(Previously Presented)**     The method as defined in claim 10, wherein connecting the plurality of leads of the lead frame connector to the corresponding conductive structures on a printed circuit board comprises:

placing the leads of the lead frame connector in contact with the corresponding conductive structures; and

connecting the leads to the conductive structures using a hot bar process.

6.     **(Original)**     The method as defined in claim 1, wherein the optical sub-assembly is a transmitter optical sub-assembly.

7.     **(Original)**     The method as defined in claim 1, wherein the optical sub-assembly is a receiver optical sub-assembly.

8.     **(Original)**     The method as defined in claim 1, wherein connecting the plurality of electrical contacts to corresponding leads includes self-alignment of the lead frame connector with respect to the optical sub-assembly as the corresponding leads pass through holes in the electrical contacts.

9.     **(Previously Presented)**     A method of manufacturing an optical transceiver module, comprising:

obtaining a lead frame connector that includes:

an electrically insulating casing; and

a plurality of conductors that are electrically isolated one from another by the electrically insulating casing, the plurality of conductors forming:

a plurality of electrical contacts that correspond to leads of the optical sub-assembly; and

a plurality of leads that correspond to conductive structures on the printed circuit board;

connecting the plurality of electrical contacts of the lead frame connector to the corresponding leads of an optical sub-assembly to obtain a combined structure that includes the lead frame connector and the optical sub-assembly; and

attaching the optical sub-assembly to a printed circuit board using the lead frame connector such that the lead frame connector electrically connects the optical sub-assembly to the printed circuit board and the lead frame connector provides mechanical support for the optical sub-assembly.

10.    **(Previously Presented)**    The method as defined in claim 1, wherein attaching the optical assembly to the printed circuit board using the lead frame connector comprises connecting a plurality of leads of the lead frame connector to corresponding conductive structures on the printed circuit board of the optical transceiver module.

11.    **(Previously Presented)**    The method as defined in claim 1, further comprising:

bending the plurality of electrical contacts at discrete segments of the electrical contacts.

12. **(Previously Presented)** The method as defined in claim 11, wherein the electrical contacts are bent at segments thereof prior to connecting the plurality of electrical contacts of the lead frame connector to corresponding leads of the optical sub-assembly.

13. **(Previously Presented)** The method as defined in claim 11, wherein the electrical contacts are bent at segments thereof prior to attaching the optical sub-assembly to the printed circuit board using the lead frame connector.

14. **(Previously Presented)** The method as defined in claim 11, wherein two of the segments of the bent electrical contacts are encased within a plastic casing.

15. **(Previously Presented)** The method as defined in claim 1, wherein a first end of each of the electrical contacts is encased in a plastic casing and a second of each of the electrical contacts is not encased and capable of being soldered to the printed circuit board.

16. **(New)** The method as defined in claim 1, wherein a bent portion of at least one of the electrical contacts is encased in a plastic casing.

17. **(New)** The method as defined in claim 16, wherein the plastic casing provides mechanical support to the bent portion of the at least one of the electrical contacts encased within the plastic casing.

18. **(New)** The method as defined in claim 1, wherein a portion of the lead frame connector between the optical subassembly and the printed circuit board is substantially rigid.

19. **(New)** The method as defined in claim 11, wherein a bent portion of at least one of the electrical contacts is encased in a plastic casing.

20. **(New)** The method as defined in claim 19, wherein the plastic casing provides mechanical stiffness to the bent portion of the at least one of the electrical contacts encased within the plastic casing.

21. **(New)** The method as defined in claim 11, wherein a portion of the lead frame connector between the optical subassembly and the printed circuit board is substantially rigid.